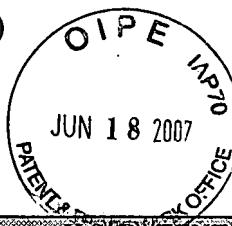


INFORMATION DISCLOSURE
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APPLICATION
(PTO-1449)

ATTY. DOCKET NO.
007734 FPS/MMCS/APCSERIAL NO.
10/665,165APPLICANT
Joseph Young J. PAIKFILING DATE
September 18, 2003

GROUP

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	3,767,900	10/23/73	Chao et al.			06/23/71
	3,920,965	11/18/75	Sohrwardy			03/04/74
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	6,094,688	07/25/00	Mellen-Garnett et al.				03/12/98
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	6,112,130	08/29/00	Fukuda et al.				10/01/97
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 007734 FPS/MMCS/APC	SERIAL NO. 10/665,165		
				APPLICANT Joseph Young J. PAIK			
				FILING DATE September 18, 2003	GROUP		
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME		CLASS	SUBCLASS	FILING DATE
	6,127,263	10/03/00	Parikh				07/10/98
	6,128,016	10/03/00	Coelho et al.				12/20/96
	6,136,163	10/24/00	Cheung et al.				03/05/99
	6,141,660	10/31/00	Bach et al.				07/16/98
	6,143,646	11/07/00	Wetzel				06/03/97
	6,148,099	11/14/00	Lee et al.				07/03/97
	6,148,239	11/14/00	Funk et al.				12/12/97
	6,148,246	11/14/00	Kawazome				06/10/98
	6,150,664	11/21/00	Su				06/29/99
	6,159,075	12/12/00	Zhang				10/13/99
	6,159,644	12/12/00	Satoh et al.				03/06/96
	6,161,054 B1	12/12/00	Rosenthal et al.				09/17/98
	6,172,756 B1	01/09/01	Chalmers et al.				12/11/98
	6,173,240 B1	01/09/01	Sepulveda et al.				11/02/98
	6,175,777 B1	01/16/01	Kim				01/16/98
	6,178,390 B1	01/23/01	Jun				09/08/98
	6,183,345 B1	02/06/01	Kamono et al.				03/20/98
	6,185,324 B1	02/06/01	Ishihara et al.				01/31/95
	6,191,864 B1	02/20/01	Sandhu				02/29/00
	6,192,291 B1	02/20/01	Kwon				10/08/98
	6,197,604 B1	03/06/01	Miller et al.				10/01/98
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	6,217,412 B1	04/17/01	Campbell et al.				08/11/99
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	6,222,936 B1	04/24/01	Phan et al.				09/13/99
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	6,240,330 B1	05/29/01	Kurtzberg et al.			05/28/97
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	2001/0003084 A1	06/07/01	Finarov			12/04/00
	6,245,581 B1	06/12/01	Bonser et al.			04/19/00
	6,246,972 B1	06/12/01	Klimasauskas			05/27/99
	6,248,602 B1	06/19/01	Bode et al.			11/01/99
	6,249,712 B1	06/19/01	Boiquaye			09/25/96
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	6,253,366 B1	06/26/01	Mutschler, III			03/31/99
	6,263,255 B1	07/17/01	Tan et al.			05/18/98
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	6,276,989 B1	08/21/01	Campbell et al.			08/11/99
	6,278,899 B1	08/21/01	Piche et al.			10/06/98
	6,280,289 B1	08/28/01	Wiswesser et al.			11/02/98
	6,284,622 B1	09/04/01	Campbell et al.			10/25/99
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	6,298,470 B1	10/02/01	Breiner et al.			04/15/99
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	6,307,628 B1	10/23/01	Lu et al.			08/18/00
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium		
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System		
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder		
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers		
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems		
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide		
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow		
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes		
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions		
	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium		
	09/943,383	08/31/01	Shanmugasundram et al.	In Situ Sensor Based Control of Semiconductor Processing Procedure		
	09/943,955	08/31/01	Shanmugasundram et al.	Feedback Control of a Chemical Mechanical Polishing Device Providing Manipulation of Removal Rate Profiles		
	09/998,372	11/30/01	Paik	Control of Chemical Mechanical Polishing Pad Conditioner Directional Velocity to Improve Pad Life		
	09/998,384	11/30/01	Paik	Feedforward and Feedback Control for Conditioning of Chemical Mechanical Polishing Pad		
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	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements		
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control		
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing		
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities		
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control		
	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes		
	10/174,377	06/18/02	Schwarm et al.	Feedback Control of Sub-Atmospheric Chemical Vapor Deposition Processes		
	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data		
	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control		
	10/632,107	08/01/03	Schwarm et al.	Method, System, and Medium for Handling Misrepresentative Metrology Data Within an Advanced Process Control System		
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
	08-50161	02/20/96	Japan			X	
	08-149583	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
	EP 0 747 795 A2	12/11/96	Europe			X	
	09-34535	02/07/97	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WO			X	
	10-34522	02/10/98	Japan			X	
	10-173029	06/26/98	Japan			X	
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	EP 0 869 652 A2	10/07/98	Europe			<input checked="" type="checkbox"/> X
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	EP 0 877 308 A2	11/11/98	Europe			<input checked="" type="checkbox"/> X
	EP 0 881 040 A2	12/02/98	Europe			<input checked="" type="checkbox"/> X
	EP 0 895 145 A1	02/03/99	Europe			<input checked="" type="checkbox"/> X
	WO 99/09371	02/25/99	WO			<input checked="" type="checkbox"/> X
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	EP 0 910 123 A1	04/21/99	Europe			<input checked="" type="checkbox"/> X
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	EP 0 932 194 A1	07/28/99	Europe			<input checked="" type="checkbox"/> X
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	2000-183001	06/30/00	Japan			<input checked="" type="checkbox"/> X
	WO 00/54325	09/14/00	WO			<input checked="" type="checkbox"/> X
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	WO 00/79355 A1	12/28/00	WO			<input checked="" type="checkbox"/> X
	EP 1 066 925 A2	01/10/01	Europe			<input checked="" type="checkbox"/> X
	EP 1 067 757 A1	01/10/01	Europe			<input checked="" type="checkbox"/> X
	EP 1 071 128 A2	01/24/01	Europe			<input checked="" type="checkbox"/> X
	WO 01/11679 A1	02/15/01	WO			<input checked="" type="checkbox"/> X
	WO 01/15865 A1	03/08/01	WO			<input checked="" type="checkbox"/> X
	WO 01/18623 A1	03/15/01	WO			<input checked="" type="checkbox"/> X
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	WO 01/25865 A1	04/12/01	WO			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
	WO 01/33501 A1	05/10/01	WO			X	
	434103	05/16/01	Taiwan			X	
	436383B	05/28/01	Taiwan			X	
	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/52319 A1	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	455938B	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
	WO 01/80306 A2	10/25/01	WO			X	
	2001-305108	10/31/01	Japan			X	
	EP 1 072 967 A3	11/21/01	Europe			X	
	2002-9030	01/11/02	Japan			X	
	EP 1 182 526 A2	02/27/02	Europe			X	
	WO 02/17150 A1	02/28/02	WO			X	
	WO 02/31613 A2	04/18/02	WO			X	
	WO 02/31613 A3	04/18/02	WO			X	
	WO 02/33737 A2	04/25/02	WO			X	
	WO 02/074491 A1	09/26/02	WO			X	
	2002-343754	11/29/02	Japan			X	

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